Halogen-free Lead-free Solder Paste

Reduce the void of the solder junction

NH series, LH series

Product lineup

Product name	Halogen content	Cl %※	Br %※
PS31BR-600-NH5	Halogen –free (No halogen)	0ppm	0ppm
PS31BR-600A-LH1	Halogen –free (IPC criteria)	700ppm	700ppm
For 0402 chip size PS31BR-750-NH3	Halogen –free (No halogen)	0ppm	0ppm

※ Flask Combustion Method

Void-less and good Wettability

Void test result

	PS31BR-600-NH5	PS31BR-600A-LH1	Conventional
BGA (0.8mmP)			
Power transistor			

Test condition
- Reflow condition：Air
- Print thickness：150μm

Wettability test result

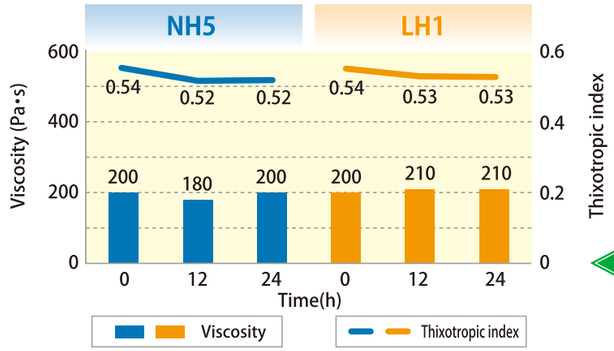
	PS31BR-600-NH5	PS31BR-600A-LH1	Conventional
Φ0.25mm land			

Test condition
- Reflow condition：Air
- Print thickness：150μm

Less void generation and excellent wettability by flux optimization

Highly stable viscosity

Viscosity and Thixotropy change

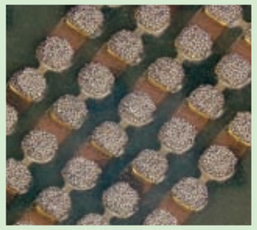
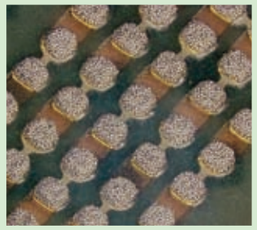


Test condition
- No replace solder paste

Small viscosity change after 24 hours of production

Correspondence to 0402 chip mounting. (PS31BR-750-NH3)

Appearance after printing for 0402 chip

	1st sheet	20th sheet
Appearance after printing		

Test condition
- Print thickness：100μm

Wettability for 0402 chip

PS31BR-750-NH3	Conventional paste

Test condition
- Reflow condition：Air

Good Wettability for 0402 chip